

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claims 1-24. (canceled)

25. (New) An electronic package comprising:

a first circuitry component having a top surface;

a second circuitry component over said top surface;

an insulation layer covering said second circuitry component and said top surface;

and

a metal layer on said insulation layer.

26. (New) The electronic package of claim 25, wherein said first circuitry component comprises a semiconductor chip.

27. (New) The electronic package of claim 25, wherein said second circuitry component comprises a semiconductor chip.

28. (New)The electronic package of claim 25 further comprising a bump between said first and second circuitry components.

29. (New)The electronic package of claim 25, wherein said insulation layer comprises a portion between said first and second circuitry components and enclosing said bump.

30. (New)The electronic package of claim 25, wherein said insulation layer comprises a photosensitive material.

31. (New)The electronic package of claim 25 further comprising a via through said insulation layer and connecting said first circuitry component and said metal layer.

32. (New)The electronic package of claim 25, wherein said insulation layer has a top surface comprising a first region and a second region, said first region being over said second circuitry component, said second region being not over said second circuitry component, wherein said first and second regions are coplanar.

33. (New)The electronic package of claim 32, wherein said metal layer is on said first and second regions.

34. (New)The electronic package of claim 25 further comprising a bump over said metal layer.

35. (New)The electronic package of claim 25, wherein said second circuitry component comprising a top surface and a bottom surface facing said top surface of said first circuitry component, said insulation layer over said top surface of said second circuitry component.

36. (New)An electronic package comprising:

a first circuitry component having a top surface;

a second circuitry component over said top surface;

an insulation layer covering said second circuitry component and said top surface;

and

a via through said insulation layer and connected to said first circuitry component.

37. (New)The electronic package of claim 36, wherein said first circuitry component comprises a semiconductor chip.

38. (New)The electronic package of claim 36, wherein said second circuitry component comprises a semiconductor chip.

39. (New)The electronic package of claim 36 further comprising a bump between said first and second circuitry components.

40. (New)The electronic package of claim 36, wherein said insulation layer comprises a portion between said first and second circuitry components and enclosing said bump.

41. (New)The electronic package of claim 36, wherein said insulation layer comprises a photosensitive material.

42. (New)The electronic package of claim 36 wherein said insulation layer has a top surface comprising a first region and a second region, said first region being over said second circuitry component, said second region being not over said second circuitry component, wherein said first and second regions are coplanar.

43. (New)The electronic package of claim 36 further comprising a bump over said via.

44. (New)The electronic package of claim 36, wherein said second circuitry component comprising a top surface and a bottom surface facing said top surface of said first circuitry component, said insulation layer over said top surface of said second circuitry component.